

Amendments to the Specification:

Please cancel the paragraph at page 3, lines 4-11, and insert the following replacement paragraph therefor:

In semiconductor manufacturing the use of cooling or heating chucks is widely known. Onto these chucks the semiconductor substrates, normally a ~~wafer~~ wafer, are clamped and by thermal contact with the (heated or cooled) chuck the substrates temperature is adjusted according to the needs of the particular processing step. However, such chucks seek to adjust temperatures homogenously over the complete area of the substrate.